BROADCOM®

Data Sheet

ASMF-PWG8-NxxxM

1W 3030 Surface Mount LED

Description

The Broadcom® ASMF-PWG8-NxxxM surface mount LEDs use InGaN chip technology with superior package design to enable them to produce higher light output with better flux performance. They can be driven at high current and are able to dissipate the heat more efficiently resulting in better performance with higher reliability.

These LEDs operate under a wide range of environmental conditions making ideal for various applications including fluorescent replacement, under cabinet lighting, retail display lighting, and panel lights.

To facilitate easy pick-and-place assembly, the LEDs are packed in tape and reel. Every reel is shipped in single flux and color bin, to provide close uniformity.

Features

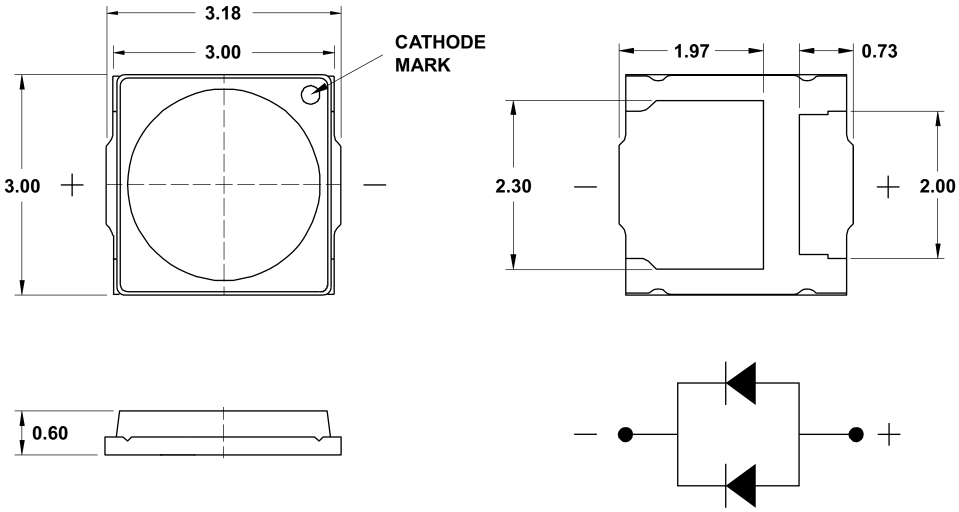
- High reliability package with enhanced silicone resin encapsulation
- Available in 2700K, 3000K, 3500K, 4000K, 5000K, 5700K, 6200K, and 6500K CCT
- Wide viewing angle at 120°
- Low package profile and large emitting area for better uniformity in linear lighting
- JEDEC MSL 3

Applications

- Retail display lighting
- Under cabinet lighting
- Indoor commercial and residential lighting
- Indoor decorative lighting

CAUTION!	This LED is ESD sensitive. Observe appropriate precautions during handling and processing. Refer to application note AN-1142 for additional details.

Figure 1: Package Drawing



NOTE:

1. All dimensions are in millimeters (mm).
2. Tolerance is ±0.20 mm unless otherwise specified.
3. Encapsulation = silicone.
4. Terminal finish = silver plating.
5. Dimensions in brackets are for reference only.

Device Selection Guide (T_J = 25°C, I_F = 300 mA)

Part Number	Correlated Color Temperature, CCT (Kelvin)	Luminous Flux, Φ_V (lm)[a, b]			Luminous Efficiency (lm/W)
	Typ.	Min.	Typ.	Max.	
ASMF-PWG8-NMPAM	2700	90.5	115.0	127.0	119.8
ASMF-PWG8-NMPBM	3000	90.5	115.0	127.0	119.8
ASMF-PWG8-NNQCM	3500	105.0	120.0	140.0	125.0
ASMF-PWG8-NPRDM	4000	115.0	128.0	154.0	133.3
ASMF-PWG8-NPREM	5000	115.0	128.0	154.0	133.3
ASMF-PWG8-NPRFM	5700	115.0	132.0	154.0	137.5
ASMF-PWG8-NPRGM	6200	115.0	132.0	154.0	137.5
ASMF-PWG8-NPRHM	6500	115.0	132.0	154.0	137.5

a. The luminous flux, Φ_V, is measured at the mechanical axis of the package and it is tested with a single current pulse condition.

b. Tolerance is ±12%..

Absolute Maximum Ratings

Parameters	ASMF-PWG8-NxxxM	Units
DC Forward Current[a]	350	mA
Peak Forward Current[b]	1000	mA
Power Dissipation	1260	mW
Reverse Voltage	Not designed for reverse bias operation	
LED Junction Temperature	125	°C
Operating Temperature Range	–40 to +85	°C
Storage Temperature Range	–40 to +100	°C

a. Derate linearly as shown in Figure 15 and Figure 16.

b. Duty factor = 10%, frequency = 1 kHz.

Optical and Electrical Characteristics (T_J = 25°C, I_F = 300 mA)

Parameters	Min.	Typ.	Max.	Units
Viewing Angle, $2\theta_{½}$[a]	—	120	—	°
Forward Voltage, V_F[b]	2.8	3.2	3.6	V
Reverse Voltage, V_R at I_R = 10 µA[c]	5.0	—	—	V
Color Rendering Index, CRI	80	—	—	—
Thermal Resistance, $R_{\theta J\text{-}S}$[d]	—	18	—	°C/W

a. $\theta_{½}$ is the off-axis angle where the luminous intensity is half of the peak intensity.

b. Forward voltage tolerance is ±0.1V.

c. Indicates product final test condition. Long term reverse bias is not recommended.

d. Thermal resistance from LED junction to solder point.

Part Numbering System

A	S	M	F	-	P	W	G	8	-	N	x_1	x_2	x_3	x_4

Code	Description	Option	
x_1	Minimum Flux Bin	See Flux Bin Limits (CAT)	
x_2	Maximum Flux Bin		
x_3	Color Correlated Temperature	A	2700K
		B	3000K
		C	3500K
		D	4000K
		E	5000K
		F	5700K
		G	6200K
		H	6500K
x_4	Test Option	M	Test Current = 300 mA

Part Number Example

ASMF-PWG8-NPRHM

x_1 : N – Minimum flux bin P
x_2 : Q – Maximum flux bin R
x_3 : H – CCT 6500K
x_4 : M – Test current = 300 mA

Bin Information

Flux Bin Limits (CAT)

Bin ID	Luminous Flux, Φ_V (lm)	
	Min.	Max.
M	90.5	105.0
N	105.0	115.0
P	115.0	127.0
Q	127.0	140.0
R	140.0	154.0

Tolerance = ± 12%.

Example of bin information on reel and packaging label:

CAT : N	–	Flux bin N
BIN : 64S	–	Color bin 64S

Color Bin Limits (BIN)

CCT	Bin ID	Chromaticity Coordinates	
		x	y
2700	27S	0.4475	0.4012
		0.4582	0.4199
		0.4708	0.4288
		0.4598	0.4041
3000	29S	0.4295	0.3918
		0.4381	0.4097
		0.4515	0.4145
		0.4420	0.3962
3500	34S	0.4006	0.3811
		0.4061	0.3980
		0.4226	0.4056
		0.4150	0.3881
4000	41S	0.3699	0.3646
		0.3743	0.3846
		0.3885	0.3934
		0.3885	0.3741
5000	50S	0.3372	0.3449
		0.3378	0.3596
		0.3496	0.3694
		0.3478	0.3533
5700	58G	0.3220	0.3280
		0.3209	0.3425
		0.3330	0.3533
		0.3329	0.3375
6200	62G	0.3133	0.3214
		0.3113	0.3350
		0.3208	0.3444
		0.3219	0.3296
6500	64S	0.3079	0.3274
		0.3068	0.3354
		0.3181	0.3467
		0.3192	0.3387

Tolerance = ± 0.01.

Figure 2: Chromaticity Diagram

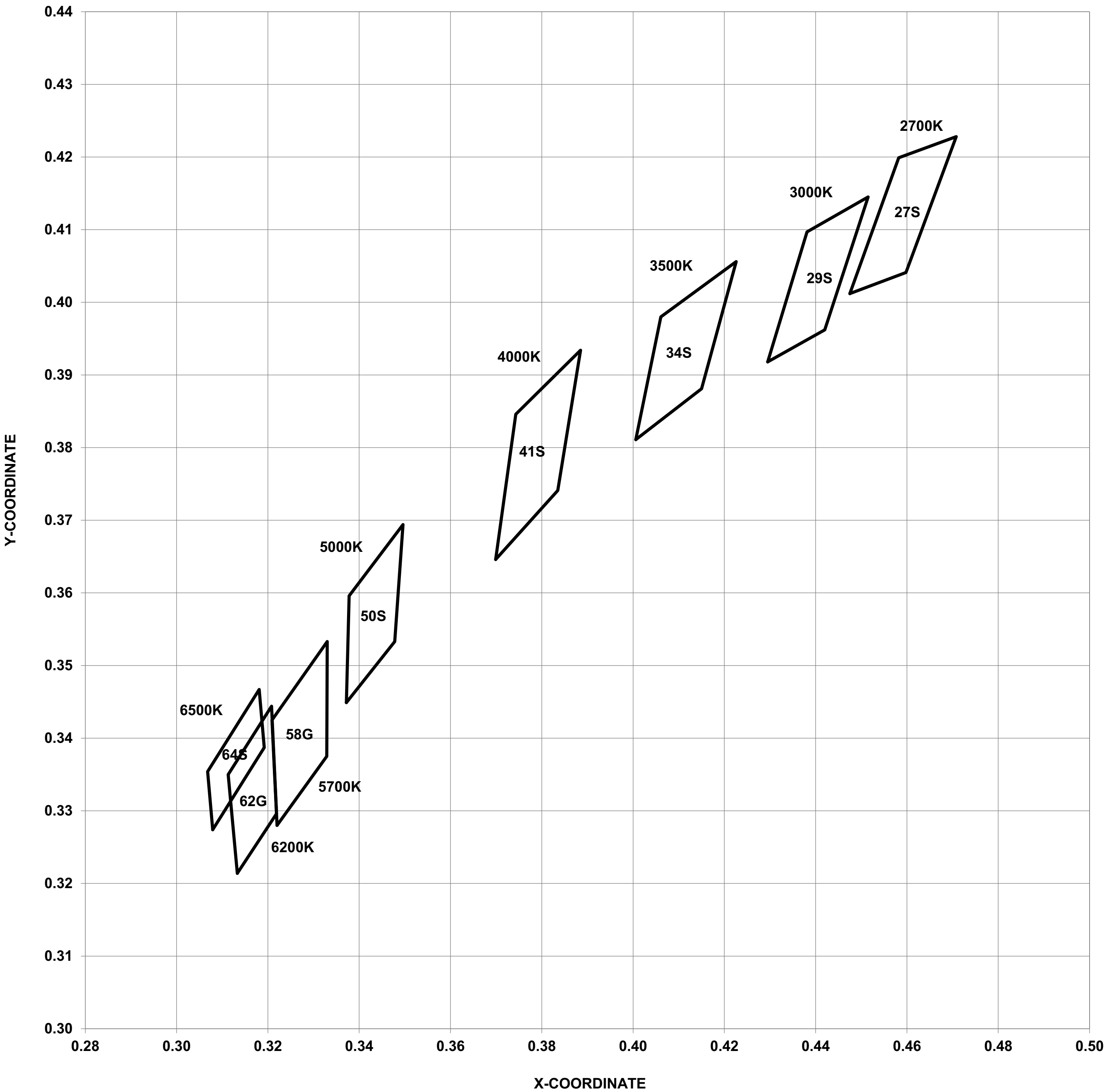


Figure 3: Spectral Power Distribution

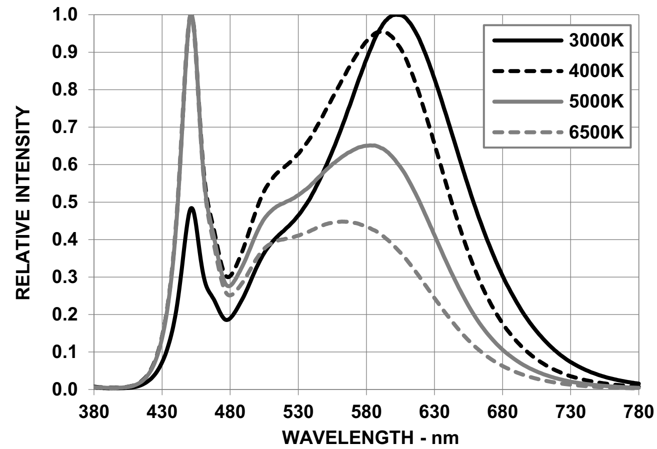


Figure 4: Forward Current vs. Forward Voltage

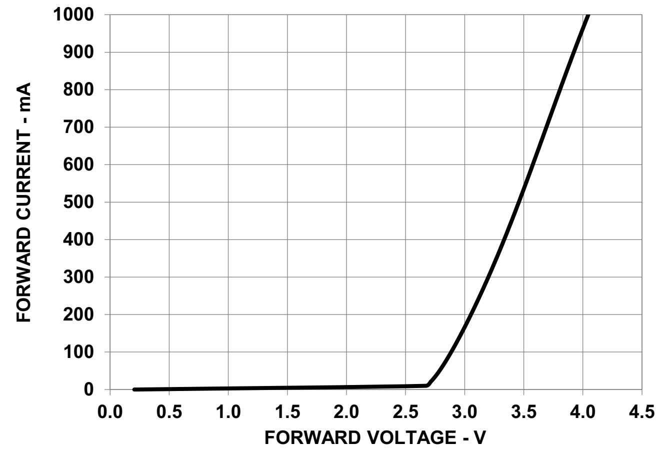


Figure 5: Relative Luminous Flux vs. Mono Pulse Current

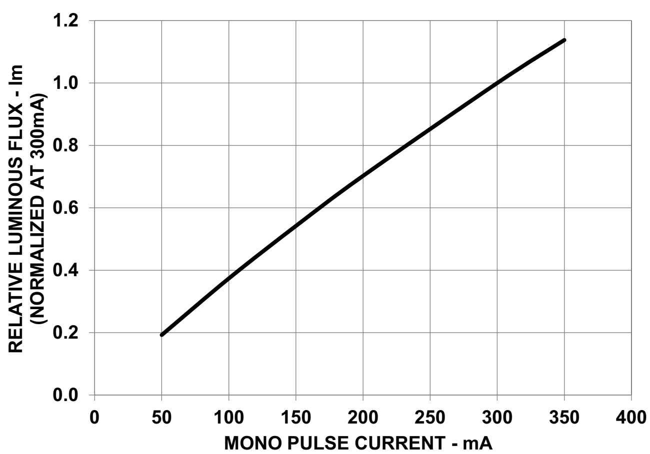


Figure 6: Radiation Pattern

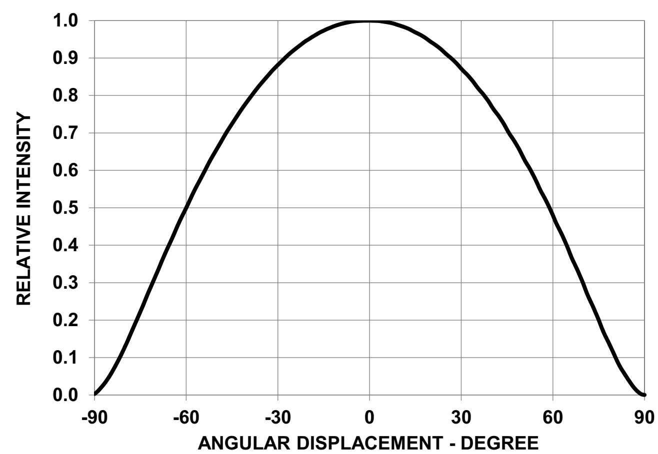


Figure 7: Chromaticity Coordinate Shift vs. Mono Pulse Current – 3000K

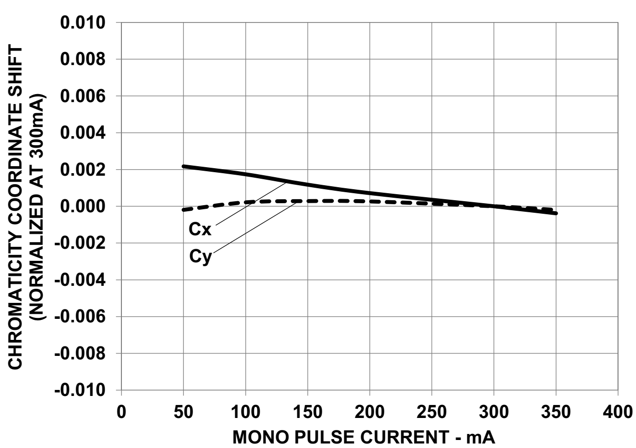


Figure 8: Chromaticity Coordinate Shift vs. Mono Pulse Current – 4000K

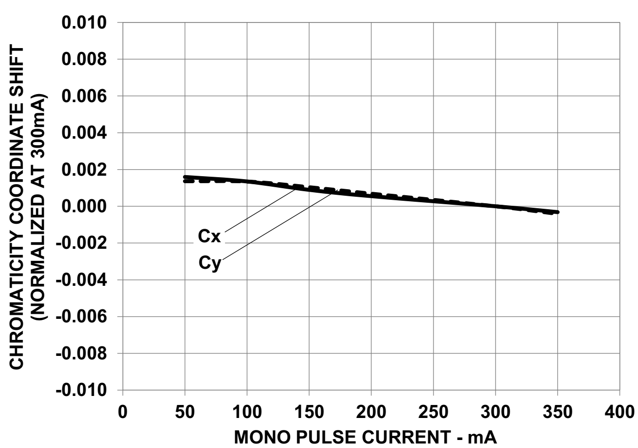


Figure 9: Chromaticity Coordinate Shift vs. Mono Pulse Current – 5000K

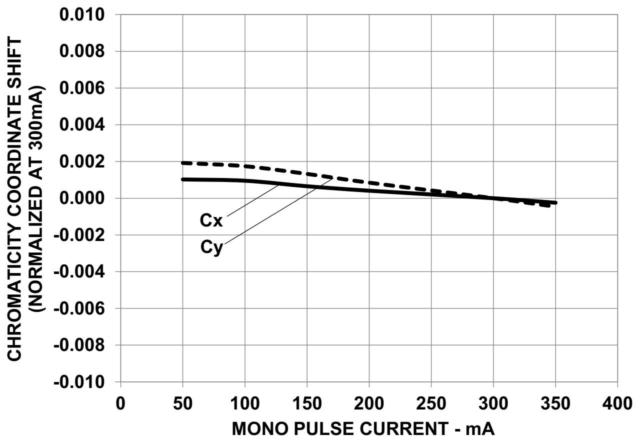


Figure 10: Chromaticity Coordinate Shift vs. Mono Pulse Current – 6500K

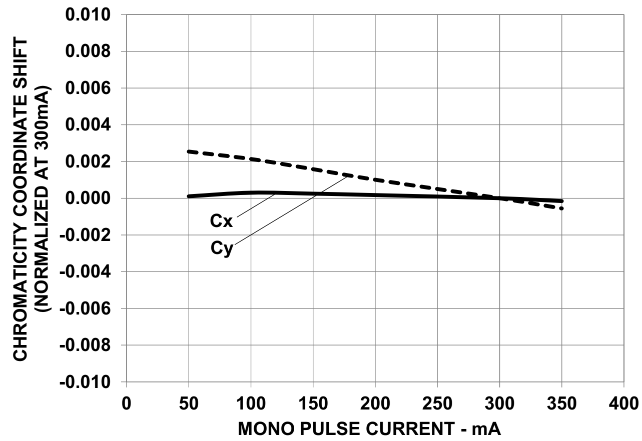


Figure 11: Relative Light Output vs. Junction Temperature

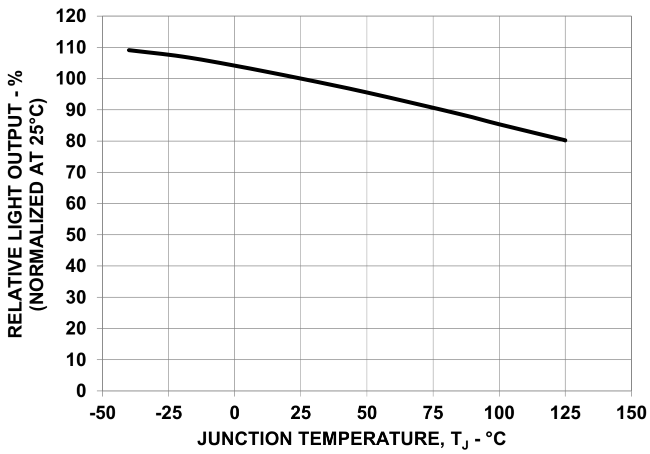


Figure 12: Forward Voltage Shift vs. Junction Temperature

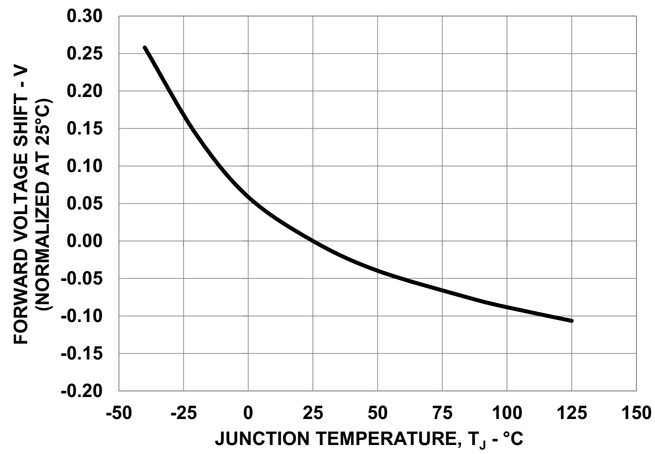


Figure 13: Chromaticity Coordinate Shift vs. Junction Temperature – 3000K

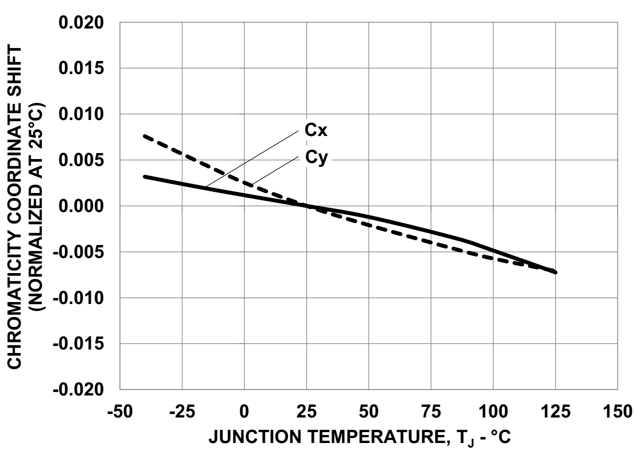


Figure 14: Chromaticity Coordinate Shift vs. Junction Temperature – 4000K, 5000K and 6500K

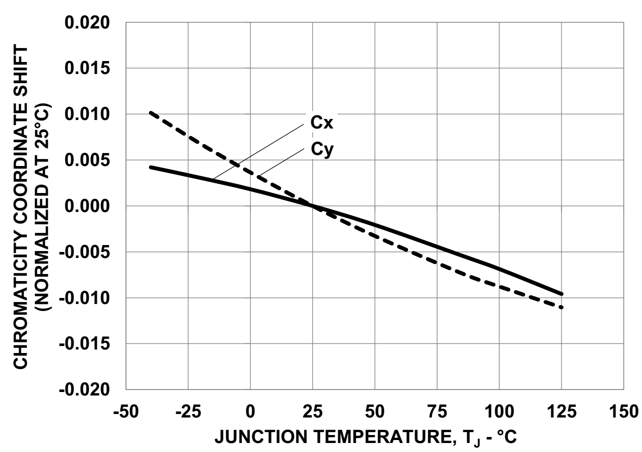


Figure 15: Maximum Forward Current vs. Ambient Temperature. Derated based on T_{JMAX} = 125°C.

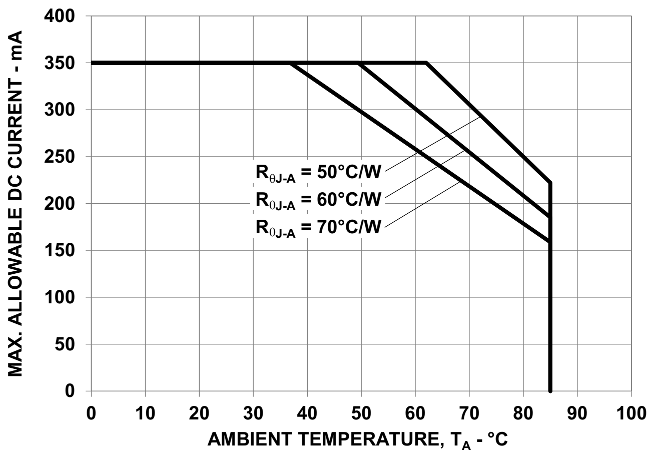


Figure 16: Maximum Forward Current vs. Solder Point Temperature. Derated based on T_{JMAX} = 125°C, $R_{\theta J-S}$ = 18°C/W.

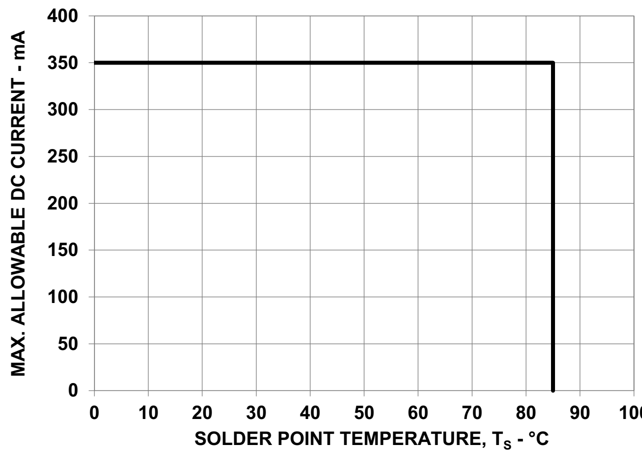
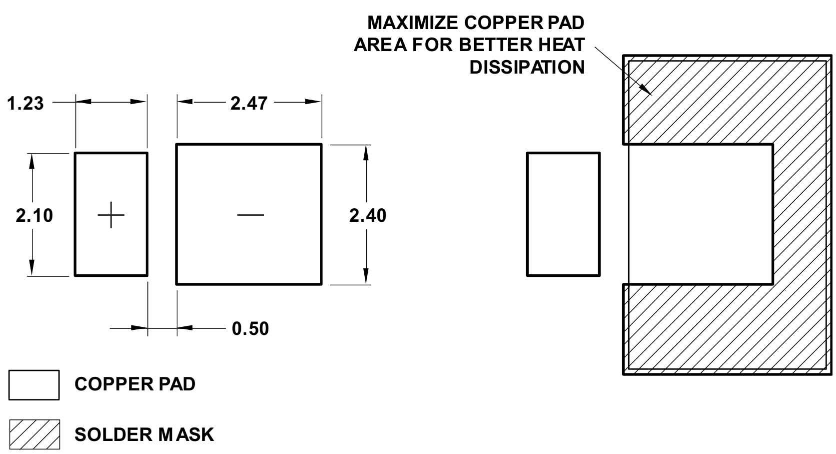
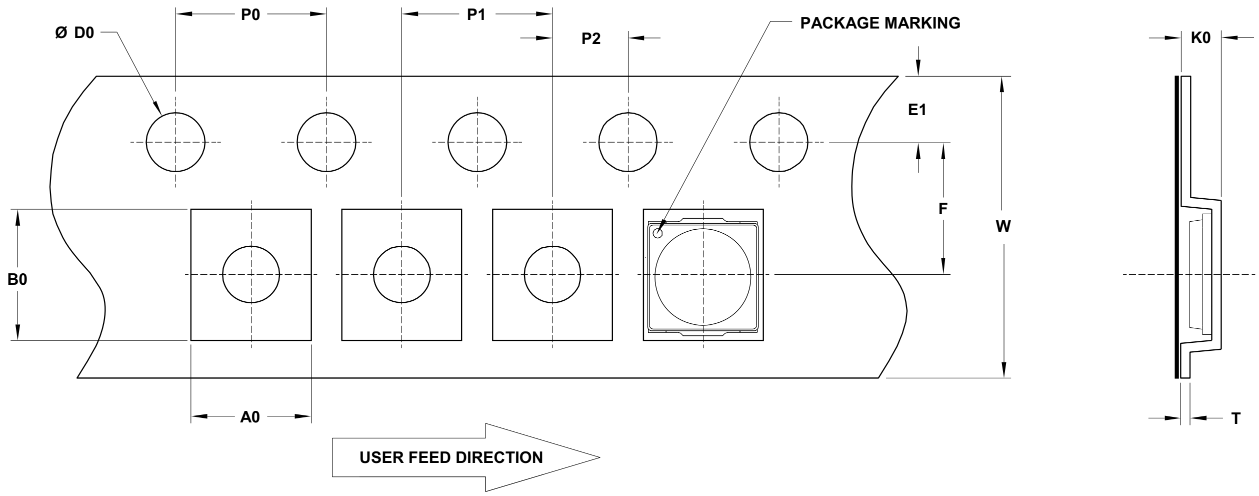


Figure 17: Recommended Soldering Land Pattern



NOTE: All dimensions are in millimeters (mm).

Figure 18: Carrier Tape Dimensions

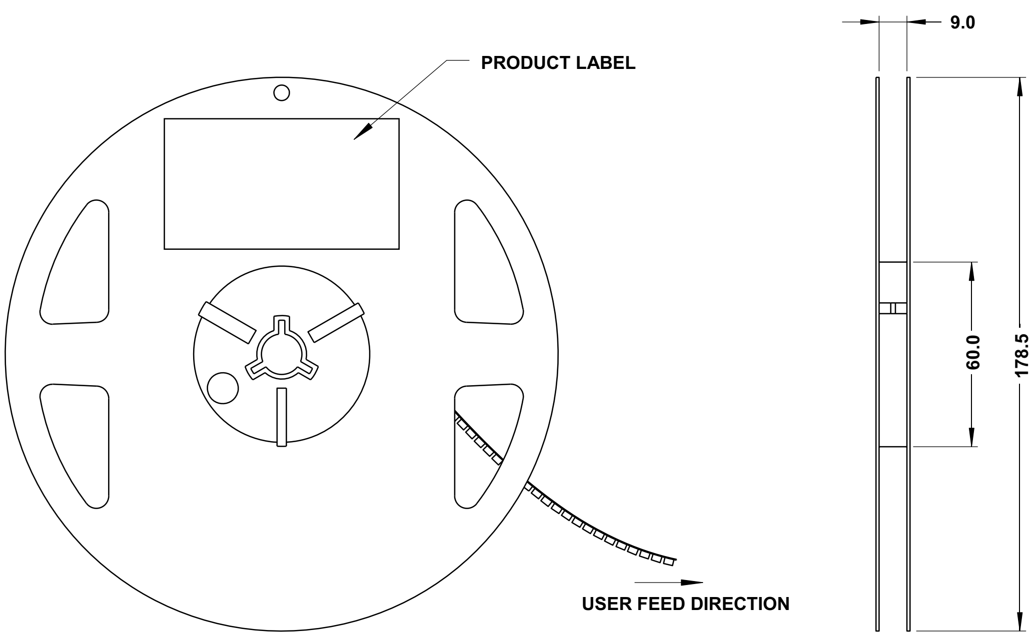


F	P0	P1	P2	D0	E1	W
3.5 ±0.05	4.0 ±0.1	4.0 ±0.1	2.0 ±0.05	1.55 +0.1	1.75 ±0.1	8.0 ±0.3

T	B0	K0	A0
0.25 ±0.05	3.5 ±0.1	0.8 ±0.05	3.3 ±0.1

NOTE: All dimensions are in millimeters (mm).

Figure 19: Reel Dimensions



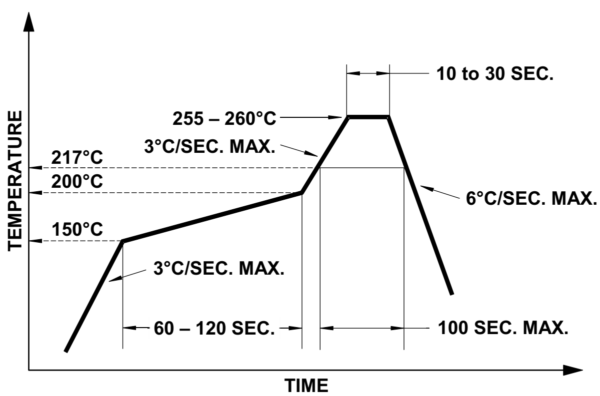
NOTE: All dimensions are in millimeters (mm).

Precautionary Notes

Soldering

- Do not perform reflow soldering more than twice. Observe necessary precautions of handling moisture-sensitive devices as stated in the following section.
- Do not apply any pressure or force on the LED during reflow and after reflow when the LED is still hot.
- Use reflow soldering to solder the LED. Use hand soldering only for rework if unavoidable, but it must be strictly controlled to following conditions:
  - Soldering iron tip temperature = 315°C maximum.
  - Soldering duration = 3 seconds maximum.
  - Number of cycles = 1 only
  - Power of soldering iron = 50W maximum.
- Do not touch the LED package body with the soldering iron except for the soldering terminals, because it may cause damage to the LED.
- Confirm beforehand whether the functionality and performance of the LED is affected by soldering with hand soldering.

Figure 20: Recommended Lead-Free Reflow Soldering Profile



Handling Precautions

The encapsulation material of the LED is made of silicone for better product reliability. Compared to epoxy encapsulant, which is hard and brittle, silicone is softer and flexible. Observe special handling precautions during assembly of silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED. Refer to Broadcom Application Note AN5288, *Silicone Encapsulation for LED: Advantages and Handling Precautions*, for additional information.

- Do not poke sharp objects into the silicone encapsulant. Sharp objects, such as tweezers or syringes, might apply excessive force or even pierce through the silicone and induce failures to the LED die or wire bond.
- Do not touch the silicone encapsulant. Uncontrolled force acting on the silicone encapsulant might result in excessive stress on the wire bond. Hold the LED only by the body.
- Do not stack assembled PCBs together. Use an appropriate rack to hold the PCBs.
- The surface of silicone material attracts dust and dirt easier than epoxy due to its surface tackiness. To remove foreign particles on the surface of silicone, use a cotton bud with isopropyl alcohol (IPA). During cleaning, rub the surface gently without putting too much pressure on the silicone. Ultrasonic cleaning is not recommended.
- For automated pick and place, Broadcom has tested a nozzle size with OD 3.5 mm to work with this LED. However, due to the possibility of variations in other parameters, such as pick-and-place machine maker/ model, and other settings of the machine, verify that the selected nozzle will not cause damage to the LED.

Handling of Moisture-Sensitive Devices

This product has a Moisture Sensitive Level 3 rating per JEDEC J-STD-020. Refer to Broadcom Application Note AN5305, *Handling of Moisture Sensitive Surface Mount Devices*, for additional details and a review of proper handling procedures.

Before use:

- An unopened moisture barrier bag (MBB) can be stored at < 40°C/90% RH for 12 months. If the actual shelf life has exceeded 12 months and the humidity indicator card (HIC) indicates that baking is not required, it is safe to reflow the LEDs per the original MSL rating.
- Do not open the MBB prior to assembly (for example, for IQC). If unavoidable, the MBB must be properly resealed with fresh desiccant and HIC. The exposed duration must be taken in as floor life.

Control after opening the MBB:

- Read the HIC immediately upon opening of the MBB.
- Keep the LEDs at < 30°/60% RH at all times, and complete all high temperature-related processes, including soldering, curing, or rework, within 168 hours.

Control for unfinished reel:

Store unused LEDs in a sealed MBB with desiccant or a desiccator at < 5% RH.

Control of assembled boards:

If the PCB soldered with the LEDs is to be subjected to other high-temperature processes, store the PCB in a sealed MBB with desiccant or desiccator at <5% RH to ensure that all LEDs have not exceeded their floor life of 168 hours.

Baking is required if the following conditions exist:

- The HIC indicates a change in color for 10% and 5%, as stated on the HIC.
- The LEDs are exposed to conditions of > 30°C/60% RH at any time.
- The LED's floor life exceeded 168 hours.

The recommended baking condition is: 60°C ± 5ºC for 20 hours.

Baking can only be done once.

Storage:

The soldering terminals of these Broadcom LEDs are silver plated. If the LEDs are exposed in an ambient environment for too long, the silver plating might be oxidized, thus affecting its solderability performance. As such, keep unused LEDs in a sealed MBB with desiccant or in a desiccator at < 5% RH.

Application Precautions

- The drive current of the LED must not exceed the maximum allowable limit across temperature as stated in the data sheet. Constant current driving is recommended to ensure consistent performance.
- The circuit design must cater to the entire range of forward voltage (V_F) of the LEDs to ensure the intended drive current can always be achieved.
- The LED exhibits slightly different characteristics at different drive currents, which may result in a larger variation of performance (such as, intensity, wavelength, and forward voltage). Set the application current as close as possible to the test current to minimize these variations.
- Do not use the LED in the vicinity of material with sulfur content or in environments of high gaseous sulfur compounds and corrosive elements. Examples of material that might contain sulfur are rubber gaskets, room-temperature vulcanizing (RTV) silicone rubber, rubber gloves, and so on. Prolonged exposure to such environments may affect the optical characteristics and product life.
- White LEDs must not be exposed to acidic environments and must not be used in the vicinity of any compound that may have acidic outgas, such as, but not limited to, acrylate adhesive. These environments have an adverse effect on LED performance.
- Avoid rapid changes in ambient temperatures, especially in high-humidity environments, because they cause condensation on the LED.
- If the LED is intended to be used in a harsh or an outdoor environment, protect the LED against damages caused by rain water, water, dust, oil, corrosive gases, external mechanical stresses, and so on.

Thermal Management

The optical, electrical, and reliability characteristics of the LED are affected by temperature. Keep the junction temperature (T_J) of the LED below the allowable limit at all times. T_J can be calculated as follows:

$$T_J = T_A + R_{\theta J\text{-}A} \times I_F \times V_{Fmax}$$

where:

T_A = Ambient temperature (°C)

$R_{\theta J\text{-}A}$ = Thermal resistance from LED junction to ambient (°C/W)

I_F = Forward current (A)

V_{Fmax} = Maximum forward voltage (V)

The complication of using this formula lies in T_A and $R_{\theta J\text{-}A}$. Actual T_A is sometimes subjective and hard to determine. $R_{\theta J\text{-}A}$ varies from system to system depending on design and is usually not known.

Another way of calculating T_J is by using the solder point temperature, T_S as follows:

$$T_J = T_S + R_{\theta J\text{-}S} \times I_F \times V_{Fmax}$$

where:

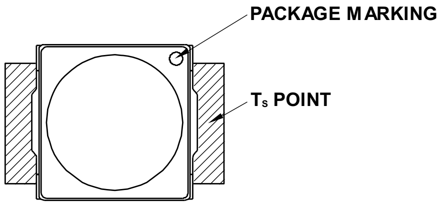
T_S = LED solder point temperature as shown in the following figure (°C)

$R_{\theta J\text{-}S}$ = Thermal resistance from junction to solder point (°C/W)

I_F = Forward current (A)

V_{Fmax} = Maximum forward voltage (V)

Figure 21: Solder Point Temperature on PCB



T_S can be easily measured by mounting a thermocouple on the soldering joint as shown in preceding figure, while $R_{\theta J\text{-}S}$ is provided in the data sheet. Verify the T_S of the LED in the final product to ensure that the LEDs are operating within all maximum ratings stated in the data sheet.

Eye Safety Precautions

LEDs may pose optical hazards when in operation. Do not look directly at operating LEDs because it might be harmful to the eyes. For safety reasons, use appropriate shielding or personal protective equipment.

Disclaimer

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Lead (Pb) Free
RoHS Compliant